

Amendments to the Claims

The current listing of the claims replaces all previous amendments and listings of the claims.

1. (Currently Amended) A power semiconductor module, comprising:

an electrode terminal connected with an electric power semiconductor device which is resin sealed inside of a case at one end while having a hole and exposed along a side of an outer surface of the case at the other end;

an electrode plate for external connection having a hole and arranged to overlie said electrode terminal on ~~an~~ the outer surface of the case;

a nut embedded in the outer surface of the case and located adjacent to a lower surface of the electrode terminal, the nut comprising a female screw hole provided ~~on the outer surface of the case so as~~ to correspond to said hole of the electrode terminal; and

a male screw member ~~having comprising~~ screw threads ~~disposed on both ends, penetrating, the male screw member comprising a small-diameter portion engaging threadedly with the female screw hole of the nut and a large-diameter portion having a diameter greater than the small diameter portion, the male screw member mounted penetratingly~~ through said hole of said electrode terminal and engaging threadedly with the female screw hole so that the male screw member is restricted at a position where a lower end of the large-diameter portion abuts against an upper surface of the nut at ~~one end~~ a side of the small-diameter portion while projecting from ~~the an~~ upper surface of the electrode terminal at ~~the other end~~ a side of the large-diameter portion,

wherein said electrode plate for external connection is electrically connected with said electrode terminal on the outer surface of the case by placing said electrode plate so that the large-diameter portion of the male screw member passes through said hole of the electrode plate, and then engaging a nut with the large-diameter portion of the male screw member.

2.-7. (Canceled)

8. (Original) The power semiconductor module according to claim 1, wherein said male screw member is threadedly engaged with said female screw hole through a plurality of electrode terminals.

9. (New) A power semiconductor module, comprising:

an electrode terminal connected with an electric power semiconductor device which is resin sealed inside of a case at one end while having a hole and exposed along a side of an outer surface of the case at the other end;

an electrode plate for external connection having a hole and arranged to overlie the electrode terminal on the outer surface of the case;

a nut embedded in the outer surface of the case and located adjacent to a lower surface of the electrode terminal, the nut comprising a female screw hole provided to correspond to the hole of the electrode terminal; and

a male screw member comprising a first portion including screw threads engaging threadedly with the female screw hole of the nut, a second portion including screw threads, and a discontinuous portion not including screw threads between the first and second portions at a middle portion of the male screw member, the male screw member mounted penetratingly through the hole of the electrode terminal and engaging threadedly with the female screw hole so that the male screw member is restricted at a position where the discontinuous portion is disposed adjacent an upper end of the female screw hole of the nut while projecting from an upper surface of the electrode terminal at a side of the second portion,

wherein the electrode plate for external connection is electrically connected with the electrode terminal on the outer surface of the case by placing the electrode plate so that the

second portion of the male screw member passes through the hole of the electrode plate, and then engaging a nut with the second portion of the male screw member.

10. (New) The power semiconductor module according to claim 9, wherein the male screw member is threadedly engaged with the female screw hole through a plurality of electrode terminals.